

Notice of References Cited

Application/Control No.
10/005,765

Applicant(s)/Patent Under
Reexamination
YANG ET AL.

Examiner
James Mitchell

Art Unit
2827

Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
A		US-4,794,092	12-1988	Solomon, Allen L.	438/109
B		US-4,784,970	11-1988	Solomon, Allen L.	438/406
C		US-6,455,398	09-2002	Fonstad et al.	438/459
D		US-6,004,867	12-1999	Kim et al.	438/459
E		US-6,013,534	01-2000	Mountain, David Jerome	438/15
F		US-6,004,867	12-1999	Kim et al.	438/459
G		US-6,322,903	11-2001	Siniaguine et al.	428/617
H		US-5,827,755	10-1998	Yonehara et al.	438/30
I		US-6,521,477	02-2003	Gooch et al.	438/106
J		US-5,185,292	02-1993	VanVonno et al.	438/59
K		US-			
L		US-			
M		US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
N						
O						
P						
Q						
R						
S						
T						

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
U		Y. T. Chen, "Localized Bonding with PSG or Indium Solder as Intermediate Layer", 1999 IEEE
V		Michael M. Maharbiz, "Balch Micropackaging by Compression-Bonded Wafer -Wafer Transfer", 1999 IEEE
W		
X		

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.